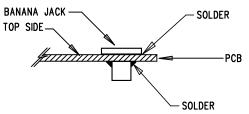
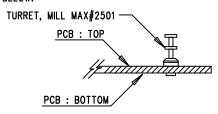
REVISION HISTORY						
EC0	REV	DESCRIPTION	APPR	DATE		
_	3	PRODUCTION	MITCHELL LEE	05-01-12		

NOTES: UNLESS OTHERWISE SPECIFIED

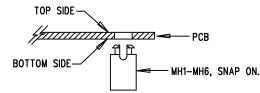
- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE SHALL BE 240 DEGREES CELSIUS.
- OMITTED (OPTIONAL) PARTS ARE SPECIFIED ON THE BILL OF MATERIALS. LAND PATTERNS FOR THESE PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL AT THESE LOCATIONS.
- 4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON ALL BOARD EDGES.
- DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
- 6. INSTALL SHUNTS AT JP1A, JP1B IN POSITIONS AS SHOWN.
- 7. INSTALL BANANA JACKS E1A,E1B,E4A,E4B,E6A,E6B,E8A,E8B AS SHOWN BELOW:



8. INSTALL TURRETS E2A,E2B,E3A,E3B,E5A,E5B,E7A,E7B, E9A,E9B AS SHOWN BELOW:



9. INSTALL 6 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPR	OVALS	1630 MCCARTHY E MILPITAS, CA 950 PH: (408)432–190	35 0
PCB DES.	M. HAWKINS	TECHNOLOGY LTC CONFIDENTIAL TECHNOLOGY LTC C	
APP ENG.	MITCHELL LEE	TITLE: ASSEMBLY DRAWING, TOP 28V/20A IDEAL DIODE AND SWI WITH REVERSE INPUT PROTECTI	
		SIZE IC NO. LTC4359HDCB N/A DEMO CIRCUIT 1676A	REV.
SCALE =	= NONE	FILENAME: DC1676A-3.PCB SHT 1	0F 2

